

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Mohd Asri YUSOF	07/29/2007
Yuen Chang CHUAH	01/02/2008
Toshihide OOBA	07/27/2007
RECEIVING PARTY DATA	
Name:	Sony EMCS (Malaysia) Sdn. Bhd.
Street Address:	Corporatehouse Service Sdn. Bhd., 22nd Floor, Wisma Cyclecarri, 288 Jalan Raja Laut
City:	Kuala Lumpur
State/Country:	MALAYSIA
Postal Code:	50350
Name:	Sony Corporation
Street Address:	1-7-1 Konan, Minato-Ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	108-0075
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11847782
CORRESPONDENCE DATA	
Fax Number:	(703)413-2220
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
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Correspondent Name:	Oblon, Spivak, et al.
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Address Line 4:	Alexandria, VIRGINIA 22314

OP \$40.00 11847782

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PATENT
REEL: 020749 FRAME: 0693

ATTORNEY DOCKET NUMBER:	312040US8X
NAME OF SUBMITTER:	Vesna Bojanic
Total Attachments: 6 source=312040USAssignment#page1.tif source=312040USAssignment#page2.tif source=312040USAssignment#page3.tif source=312040USAssignment#page4.tif source=312040USAssignment#page5.tif source=312040USAssignment#page6.tif	

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name are listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in
CABLE OR CORD WINDER

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony EMCS (Malaysia) Sdn. Bhd. with offices at Corporatehouse Service Sdn. Bhd., 22nd Floor, Wisma Cyclecarri, 288 Jalan Raja Laut, 50350 Kuala Lumpur, Malaysia and Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku, Tokyo, 108-0075 Japan (hereinafter referenced as ASSIGNEES) are desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, their successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEES, as the assignees of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or their designee, as ASSIGNEES or their successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEES thereof shall hereafter require and prepare at their own expense;

And I further agree that ASSIGNEES will, upon their request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number:
 Filing Date:

This assignment executed on the dates indicated below.

Mohd Asri YUSOF

Name of first or sole inventor

Execution date of U.S. Patent Application

Kuala Lumpur, Malaysia

Residence of first or sole inventor

Signature of first or sole inventor

29.07.07

Date of this assignment

MAC

Yuen Chang CHUAH

Name of second inventor

Execution date of U.S. Patent Application

Kuala Lumpur, Malaysia

Residence of second inventor

Signature of second inventor

Date of this assignment

Toshihide OOBA

Name of third inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of third inventor

Signature of third inventor

Date of this assignment

MAL

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Name of first or sole inventor

Execution date of U.S. Patent Application

Kuala Lumpur, Malaysia

Residence of first or sole inventor

Signature of first or sole inventor

Date of this assignment

mal

Yuen Chang CHUAH

Name of second inventor

Execution date of U.S. Patent Application

Kuala Lumpur, Malaysia

Residence of second inventor

x 

Signature of second inventor

January 2, 2008

Date of this assignment

Toshihide Ooba

Name of third inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of third inventor

Signature of third inventor

Date of this assignment

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Kuala Lumpur, Malaysia

Residence of first or sole inventor

Signature of first or sole inventor

Date of this assignment

Yuen Chang CHUAH

Name of second inventor

Execution date of U.S. Patent Application

Kuala Lumpur, Malaysia

Residence of second inventor

Signature of second inventor

Date of this assignment

Toshihide OOBA

Name of third inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of third inventor

Toshihide Ooba
Signature of third inventor

July 27th, 2007
Date of this assignment